



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **L0108-01R1** DATE: **12/10/01**
Product Affected: IDTQS3VH125, IDTQS3VH126,
IDTQS3VH257, IDTQS3VH2245,
IDTQS32XVH2245, IDTQS34XVH2245
Date Effective: **November 13, 2001**

MEANS OF DISTINGUISHING CHANGED DEVICES:

- ☐ Product Mark
☐ Back Mark
☒ Date Code Prefix "YQ", "ZQ" or "QC" to "Z"
☐ Other

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Attachment: ☒ Yes ☐ No

Samples: Available upon request

DESCRIPTION AND PURPOSE OF CHANGE:

- ☐ Die Technology
☐ Wafer Fabrication Process PCN addendum to correct PCN # L0108-01 for die revision details Die revision "XQ" should be replaced with "YQ" or "ZQ" as follow:
☐ Assembly Process
☐ Equipment
☐ Material **YQ:** IDTQS3VH125, IDTQS3VH126
☐ Testing **ZQ:** IDTQS3VH257, IDTQS3VH2245, IDTQS32XVH2245, IDTQS34XVH2245
☐ Manufacturing Site
☐ Data Sheet The PCN effectivity date is November 13, 2001 (same as the original PCN).
☒ Other

RELIABILITY/QUALIFICATION SUMMARY:

There will be no impact or effect on the product reliability. The qualification data is attached.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____

☐ **Approval for shipments prior to effective date.**

Name/Date: _____

E-Mail Address: _____

Title: _____

Phone# /Fax# : _____

CUSTOMER COMMENTS:

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____

DATE: _____



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ATTACHMENT - PCN #: L0108-01R1 (Addendum)

PCN Type: Die revision

Data Sheet Change No

Detail of Change The die has been revised from "YQ" , "ZQ" and "QC" stepping to "Z" stepping

Die Revision Details

	<u>Current Die Rev</u>	<u>Current Die Rev</u>	<u>Current Die Rev</u>	<u>New Die Rev</u>
	YQ	ZQ	QC	Z
Wafer Fab Technology	0.8µm	0.8µm	0.8µm	0.8µm
Poly Gate	0.8µm	0.8µm	0.8µm	0.8µm
Minimum Gate Oxide Thickness	150Å	150Å	150Å	150Å
Wafer Size	6"	6"	6"	6"
Fab Facility	Fab 5	Fab 5	Fab 2	Fab 2
	(PSA, Australia)	(PSA, Australia)	(Salinas, CA)	(Salinas, CA)
Date Code Prefix	YQ	ZQ	QC	Z
Affected Parts	IDTQS3VH125 IDTQS3VH126	IDTQS3VH257 IDTQS3VH2245 IDTQS32XH2245 IDTQS34XVH2245	IDTQS3VH125 IDTQS3VH126 IDTQS3VH257 IDTQS3VH2245 IDTQS32XVH2245 IDTQS34XVH2245	IDTQS3VH125 IDTQS3VH126 IDTQS3VH257 IDTQS3VH2245 IDTQS32XVH2245 IDTQS34XVH2245



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PRODUCT/PROCESS CHANGE NOTICE (PCN)
ATTACHMENT - PCN #: L0108-01R1 (Addendum)

Qualification Plan QLG-01-01

Test Vehicle: IDTQS3VH862

Qualification Test Plan and Results:

Test Description	SS/Acc #	Test Results
Dynamic High Temp Operating Life Test Mil-Std-883, Method-1005	116/0	116/0
ESD - HBM Mil-Std-883, Method-3015	3/0	3500 Volts
ESD-CDM JESD22-C101	3/0	1000 Volts
ESD-MM EIAJ-IC-121	3/0	400 Volts
Latch-up EIA/JESD78	10/0	10/0

Characterization Data:

Characterization data is available upon request.